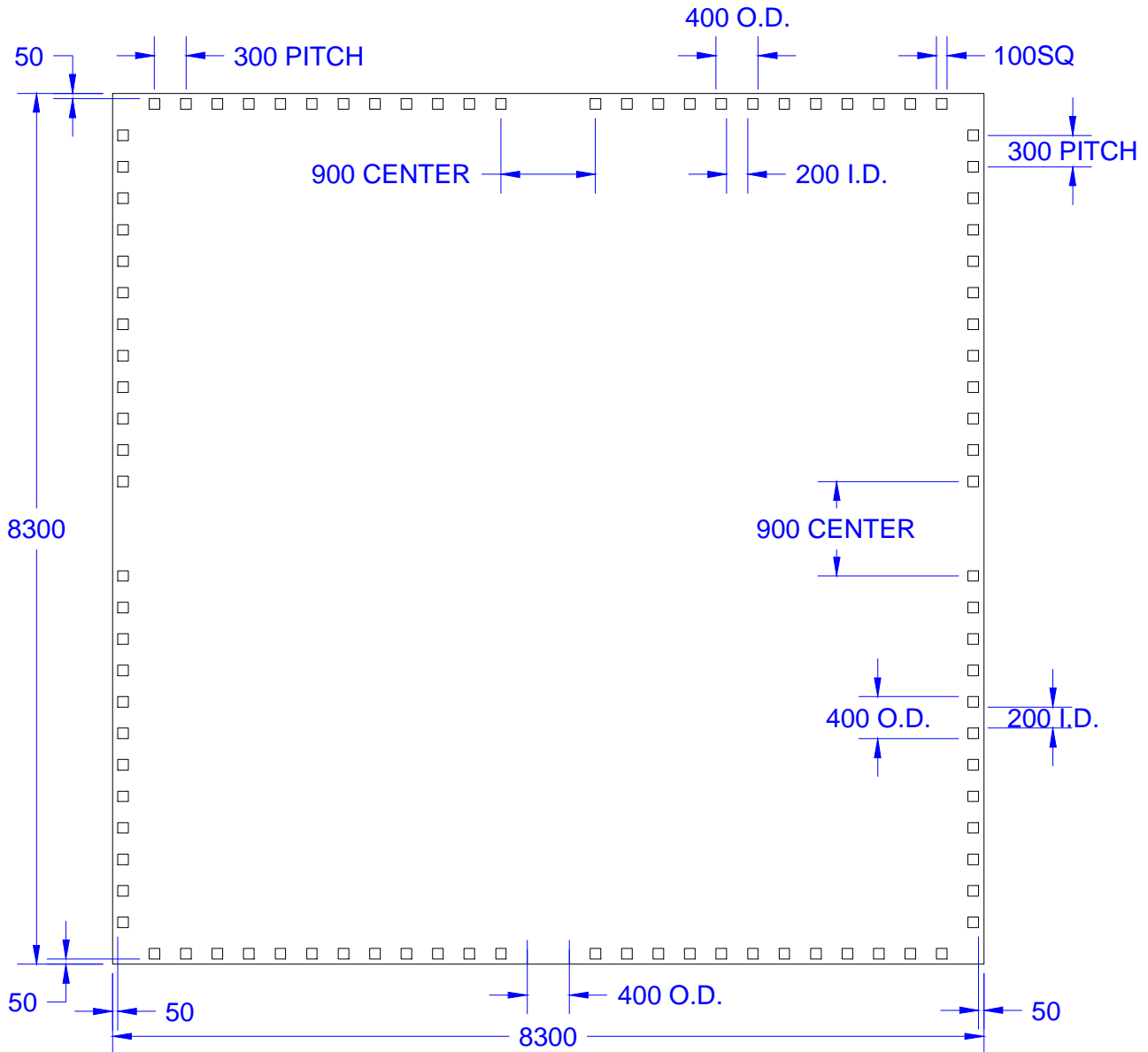


Notes: (Unless Otherwise Specified).

1. DIE MATERIAL IS SILICON.
2. DIE THICKNESS 250um ~ 725um.
3. METALLIZATION 1.0 um ALUMINUM (Al).
4. DIE IS WITHOUT PASSIVATION.
5. WIRE BONDABLE WITH GOLD (Au) WIRE.
6. DAISY CHAIN PAIRS.
7. SAW BLADE 100um.

<b>TopLine<sup>®</sup></b>			
TITLE DAISY CHAIN TEST DIE TD96 8.3x8.3MM			
SCALE	SIZE	DRAWING NO.	REV
	A	158296	A
DO NOT SCALE DRAWING			SHEET 1 OF 3

PERIMETER PAD TEST DIE  
DAISY CHAIN

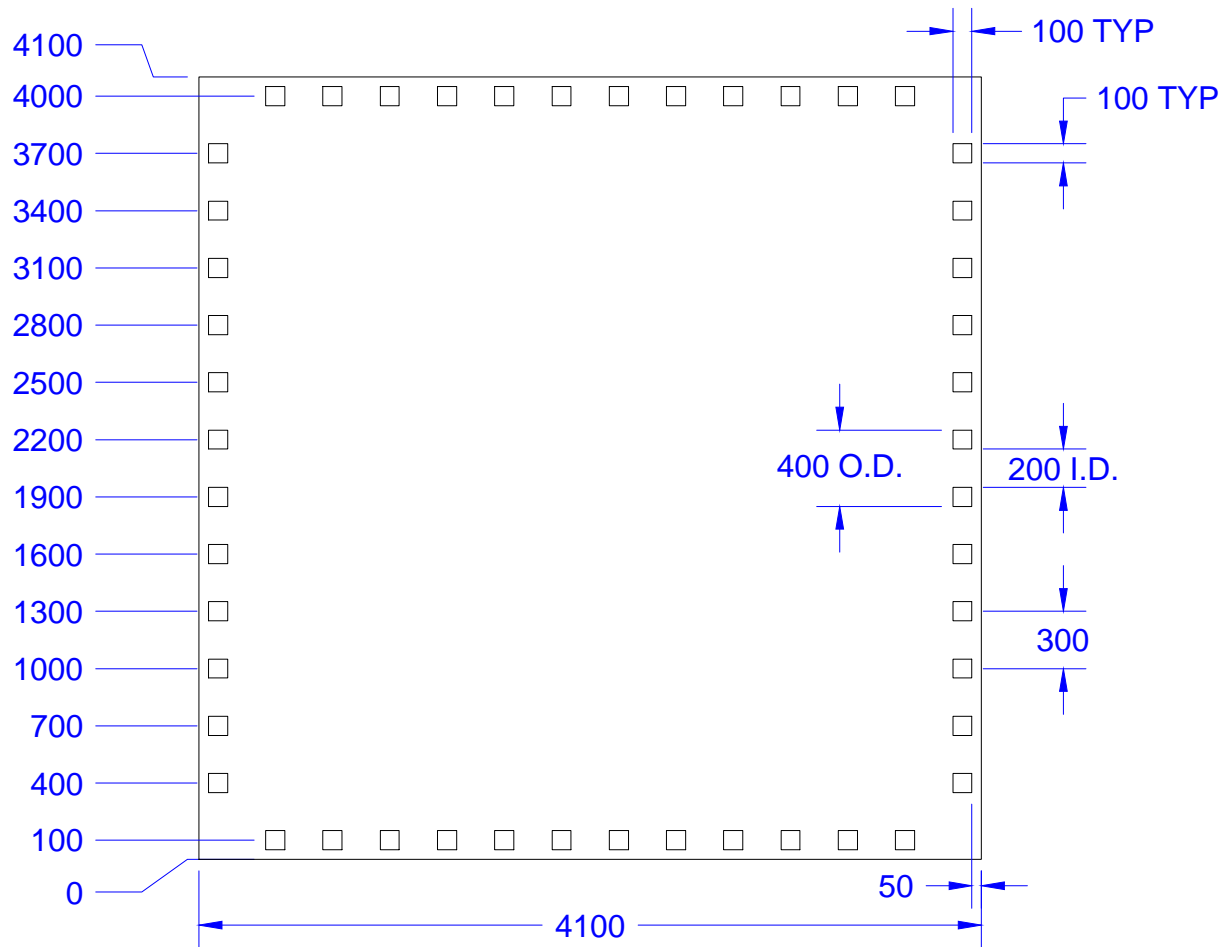


Notes: (Unless Otherwise Specified).

1. DIE MATERIAL IS SILICON.
2. DIE THICKNESS 250um ~ 725um.
3. METALLIZATION 1.0 um ALUMINUM (Al).
4. DIE IS WITHOUT PASSIVATION.
5. WIRE BONDABLE WITH GOLD (Au) WIRE.
6. DAISY CHAIN PAIRS.

DIMENSIONS IN MICRONS  
1000 um = 1.0 mm

APPROVALS	DATE	<b>TopLine®</b>			
DRAWN T. Au	04/27/13				
ENG M. Hart	04/27/13	TITLE DAISY CHAIN TEST DIE			
MFG		TD96 8.3x8.3MM			
QA		SCALE	SIZE	DRAWING NO.	REV
CUST			A	158296	A
REVISED		DO NOT SCALE DRAWING			SHEET 2 OF 3




Notes: (Unless Otherwise Specified).

1. DIE MATERIAL IS SILICON.
2. METALLIZATION 1.0  $\mu$ m ALUMINUM (Al).
3. DIE IS WITHOUT PASSIVATION.
4. WIRE BONDABLE WITH GOLD (Au) OR ALUMINUM (Al) WIRE.
5. ISOLATED PADS 100 $\mu$ m SQUARE (48 PLACES).

DIMENSIONS IN MICRONS  
1000  $\mu$ m = 1.0 mm

PART NUMBER SYSTEM						
TD	-	48	-	4.1	-	ISO
SILICON		BOND		DIE SIZE		ISOLATED
TEST DIE		PADS		(mm)		PADS

APPROVALS		DATE				
DRAWN	T. Au	04/27/13				
ENG	M. Hart	04/27/13	TITLE Si TEST DIE TD48 4.1x4.1MM			
MFG						
QA			SCALE	SIZE	DRAWING NO.	REV
CUST				A	154148	A
REVISED			DO NOT SCALE DRAWING			SHEET 3 OF 3